

1 Characteristics

Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Parameter		Value	Unit
V _{RRM}	Repetitive peak reverse voltage, T _j = -40 °C to +175 °C		100	V
I _{F(RMS)}	Forward rms current		10	A
I _{F(AV)}	Average forward current	T _c = 165 °C, δ = 0.5	5	A
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal	75	A
P _{ARM}	Repetitive peak avalanche power	t _p = 10 μs, T _j = 125 °C	518	W
T _{stg}	Storage temperature range		-65 to +175	°C
T _j	Operating junction temperature range ⁽¹⁾		-40 to +175	°C

1. $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal parameters

Symbol	Parameter	Max. value	Unit
R _{th(j-c)}	Junction to case	2.5	°C/W

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}	-		3.5	μA
		T _j = 125 °C		-	1.3	4.5	mA
V _F ⁽²⁾	Forward voltage drop	T _j = 25 °C	I _F = 5 A	-		0.73	V
		T _j = 125 °C		-	0.57	0.61	
		T _j = 25 °C	I _F = 10 A	-		0.85	
		T _j = 125 °C		-	0.66	0.71	

1. Pulse test: t_p = 5 ms, δ < 2%

2. Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses, use the following equation:

$$P = 0.51 \times I_{F(AV)} + 0.02 \times I_{F(RMS)}^2$$

1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current

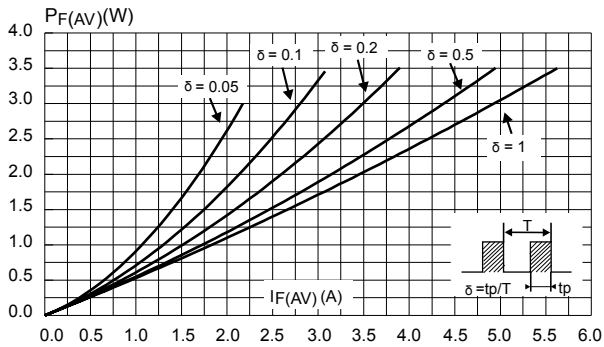


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$)

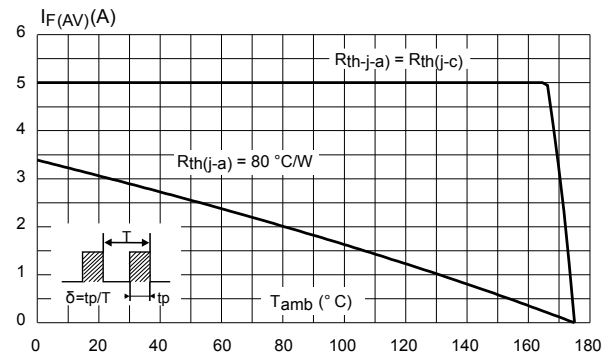


Figure 3. Normalized avalanche power derating versus junction temperature ($T_j = 125^\circ\text{C}$)

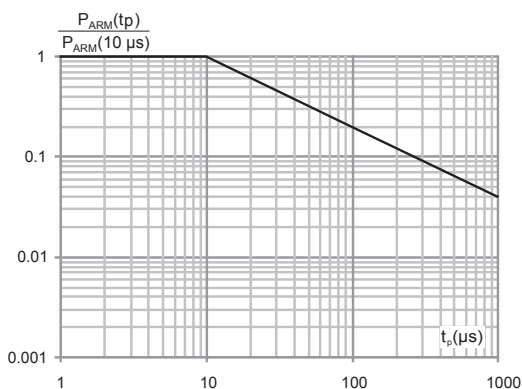


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

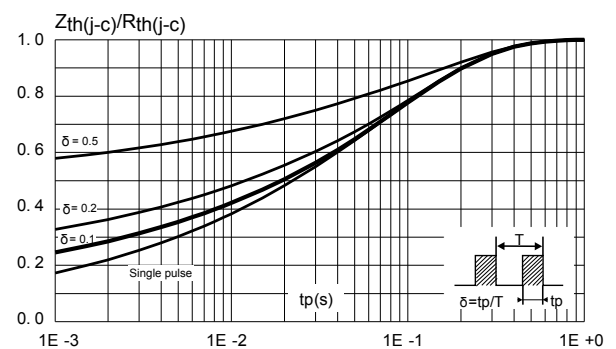


Figure 5. Reverse leakage current versus reverse voltage applied (typical values)

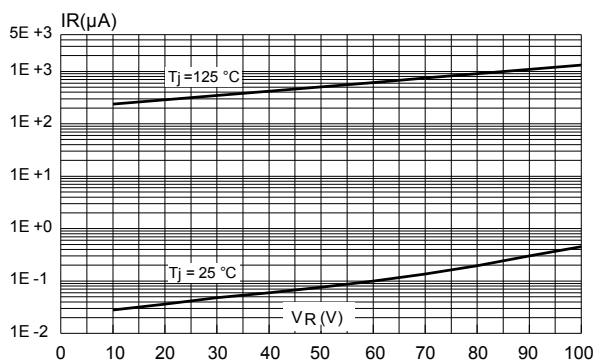


Figure 6. Junction capacitance versus reverse voltage applied (typical values)

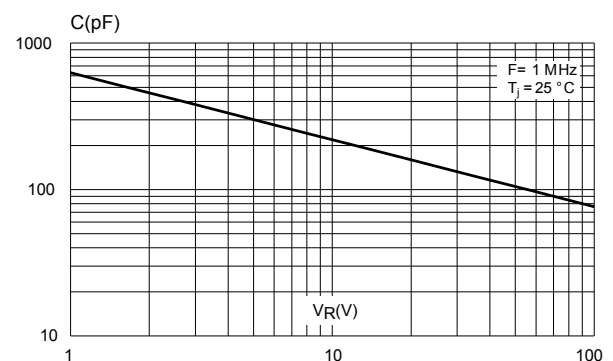


Figure 7. Forward voltage drop versus forward current (maximum values)

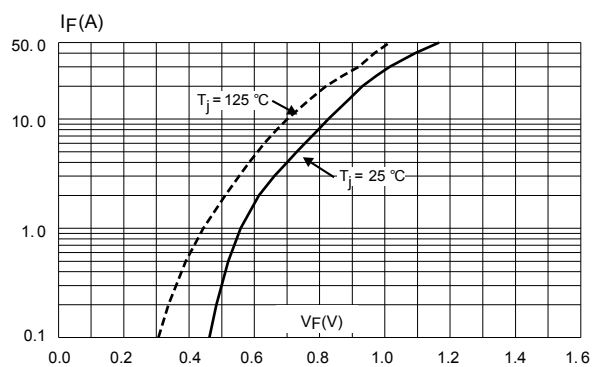
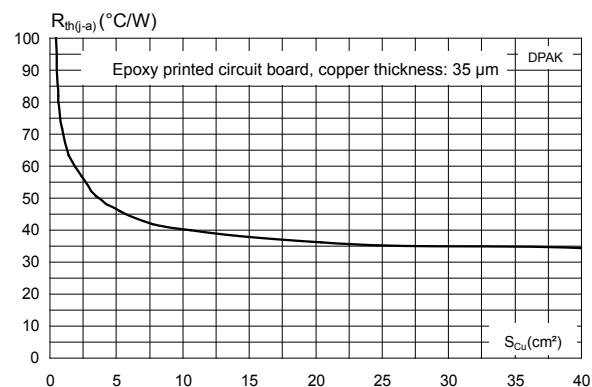


Figure 8. Thermal resistance junction to ambient versus copper surface under tab



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 DPAK package information

- Epoxy meets UL94, V0
- Lead-free packages

Figure 9. DPAK package outline

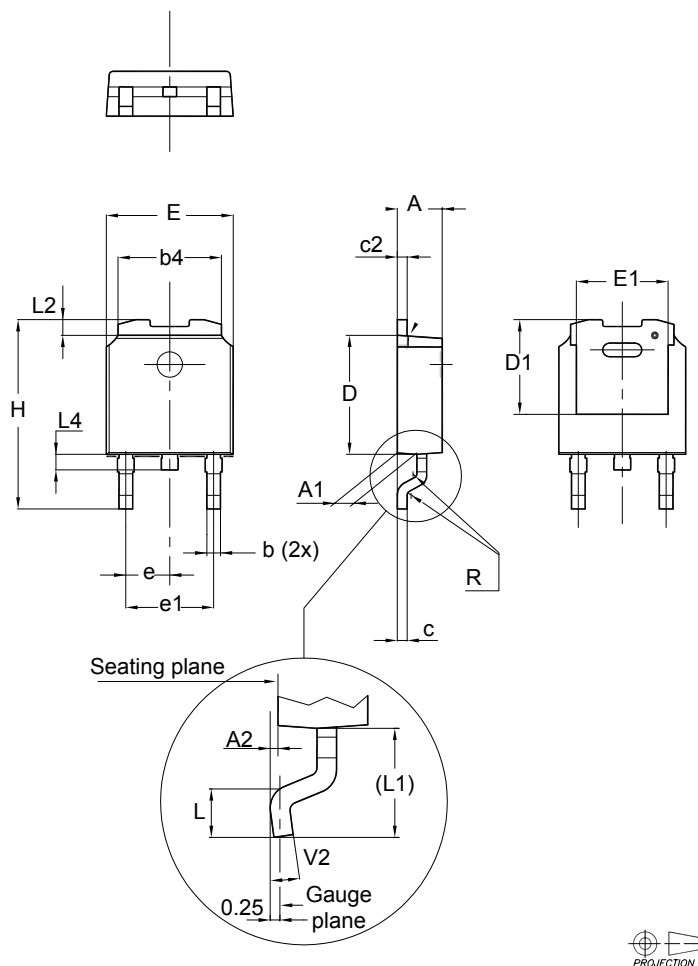
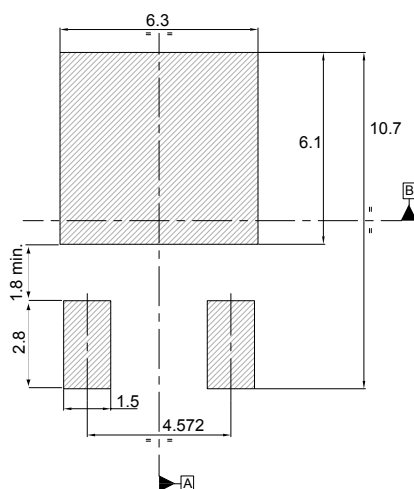


Table 4. DPAK mechanical data

Dim.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
b	0.64		0.90	0.025		0.035
b4	5.20		5.40	0.205		0.213
c	0.45		0.60	0.018		0.024
c2	0.48		0.60	0.019		0.024
D	6.00		6.20	0.236		0.244
D1	4.95	5.10	5.25	0.195	0.201	0.207
E	6.40		6.60	0.252		0.260
E1	4.60	4.70	4.80	0.181	0.185	0.189
e	2.16	2.28	2.40	0.085	0.090	0.094
e1	4.40		4.60	0.173		0.181
H	9.35		10.10	0.368		0.398
L	1.00		1.50	0.039		0.059
(L1)	2.60	2.80	3.00	0.102	0.110	0.118
L2	0.65	0.80	0.95	0.026	0.031	0.037
L4	0.60		1.00	0.024		0.039
R		0.20			0.008	
V2	0°		8°	0°		8°

Figure 10. DPAK recommended footprint (dimensions are in mm)

The device must be positioned within $\Phi 0.05 \text{ A B}$

3 Ordering information

Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS5H100BY-TR	S5H100Y	DPAK	0.30 g	2500	Tape and reel

Revision history

Table 6. Document revision history

Date	Version	Changes
07-Nov-2011	1	Initial release.
06-Apr-2018	2	Removed figure 4 and figure 5. Updated Section • Features and Section • Description. Updated Figure 3. Normalized avalanche power derating versus junction temperature ($T_j = 125\text{ °C}$) and Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified). Minor text changes to improve readability.

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